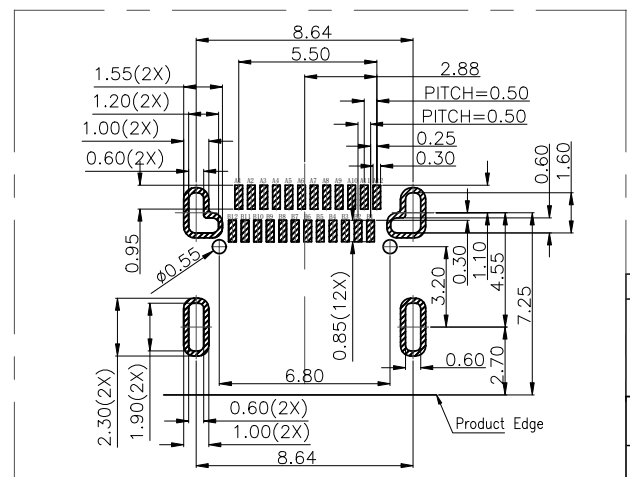
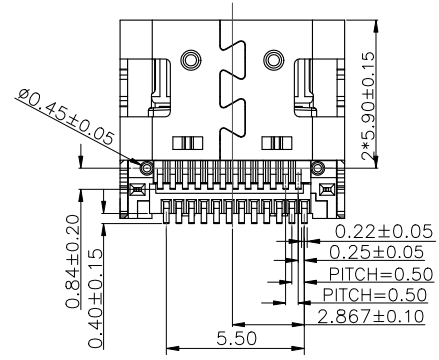
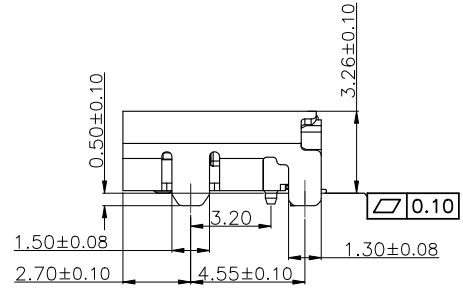
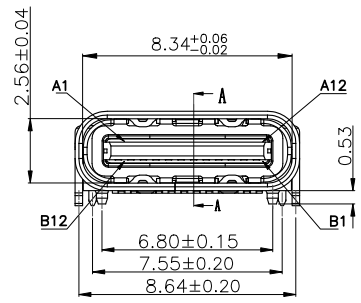
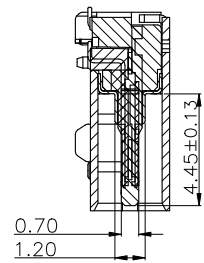
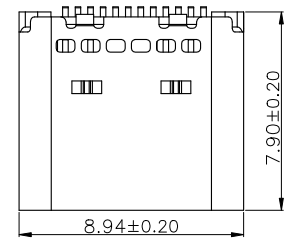
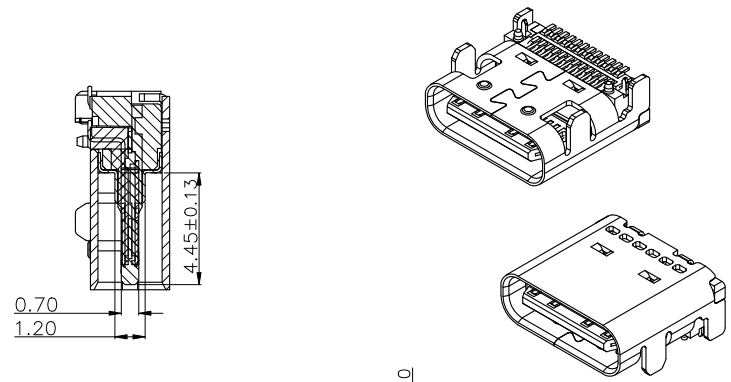


NO.	ECN NO.	DESCRIPTION	REV.	DRAW	DATE
1					
2					
3					

NOTE:
1.MATERIAL SPECIFICATION:
 1-1.HOUSING:LCP,UL94 V-0 BLACK;
 1-2.CONTACTS: COPPER ALLOY;
 1-3.MID PLATE: STAINLESS STEEL;
 1-4.FRONT SHELL: STAINLESS STEEL;
2.PLATING SPECIFICATION:
 2-1.CONTACTS:
 Ni 50u", UNDER PLATED OVER ALL.
 Au PLATED ON THE FUNCTIONAL AREA OF CONTACT.
 (GOLD PLATING THICKNESS FOLLOW THE P/N)
 PLATING SPECIFICATIONS OF THE SOLDER AREA Fu"
 2-2.FRONT SHELL:
 Ni 50u", UNDER PLATED OVER ALL.
2-3.MID PLATE&EMI PLATE:
 CLEAR ONLY
3.MECHANICAL PERFORMANCE,
 3-1.INSERTION FORCE: 0.5~2.0kgf.
 3-2.REMOVAL FORCE: 0.8kgf~2.0kgf.
 3-3.DURABILITY: 10000 CYCLES(0.6kgf~2.0kgf).
4.ELECTRICAL PERFORMANCE,
 4-1. CURRENT RATING:5A
 VOLTAGE RATING:20V
 4-2. LLCR:
 VBUS & GND PINS AND OTHER PINS: 40mΩ/PIN MAX.
 SHIELD: 50mΩ/MAX.
 LLCR MAX. CHANGE OF ALL PINS: 10mΩ.
 4-3.INSULATION RESISTANCE: 100MΩ MIN
 4-4.DIELECTRIC WITHSTAND VOLTAGE,AC 100V FOR 1 MINUTE.
5. ENVIRONMENTAL PERFORMANCE:
 OPERATING TEMPERATURE: -40°C~+85°C.
08639-0X J XX 9

RoHS COMPLIANT.
 PLATING CODE:
 05: Au G/Fu"
 PLATING SPECIFICATION:
 J: HALF THE GOLD NI

TYPE SERIAL NUMBER
 PRODUCT SERIAL NUMBER
 USB TYPE



A1	GND	B12	GND
A2	SSTXP1	B11	SSRXP1
A3	SSTXN1	B10	SSRXN1
A4	VBUS	B9	VBUS
A5	CC1	B8	SBU2
A6	DP1	B7	DN2
A7	DN1	B6	DP2
A8	SBU1	B5	CC2
A9	VBUS	B4	VBUS
A10	SSRXN2	B3	SSTXN2
A11	SSRXP2	B2	SSTXP2
A12	GND	B1	GND
PIN	SIGNAL NAME	PIN	SIGNAL NAME

RECOMMENDED P.C.B. LAYOUT
 TOLERANCE UNSPECIFIED ±0.05mm

产品客户图 Customer Drw		
未注公差 TOLERANCE UNLESS OTHERWISE SPECIFIED	X	±0.45
	.X	±0.35
	.XX	±0.25
	X°	±3°

GLGNET ® 深圳市方向电子股份有限公司 SHEN ZHEN GLGNET ELECTRONICS CO., LTD.							
比例 SCALE	1:1	角法 PROJ.	设计 DESIGN	HU G, L	20230112	品名 TITLE	USB-SMT90-M-C30-24P-A1-00
张数 SHEET	1/1	大小 SIZE	A4	校对 CHECKED		料号 ITEM NO.	140143-00111 (08639-00J059)
单位 UNIT	mm	版本 REV.	A0	核准 APPROVED		图号 DWG NO.	GLG-140143